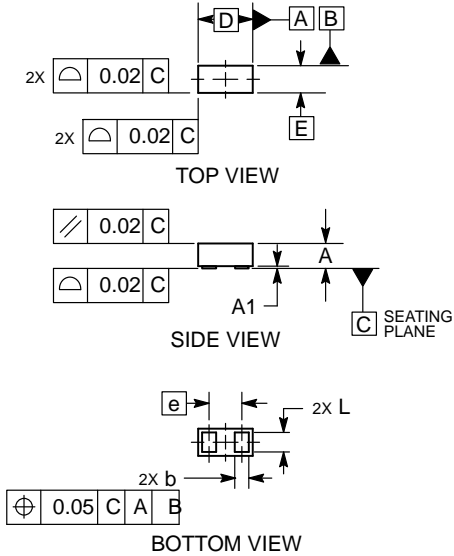




SCALE 12:1

WLCSP2, 0.6x0.3  
CASE 567AV  
ISSUE C

DATE 22 SEP 2017



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.250	0.275	0.300
A1	0.000	0.025	0.050
b	0.140	0.155	0.170
D	0.570	0.600	0.630
E	0.270	0.300	0.330
e	0.36 BSC		
L	0.190	0.215	0.240

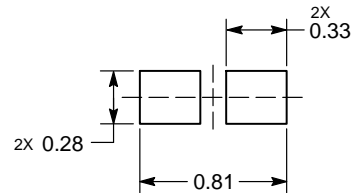
GENERIC MARKING DIAGRAM\*



X = Specific Device Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb iFree indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDER FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb iFree strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON49805E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	WLCSP2, 0.6X0.3	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.